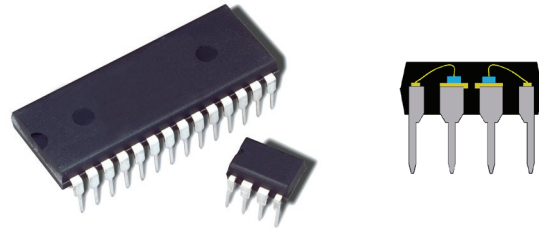


# DIP

## Dual Inline Package

Dual Inline Packages (DIP) are industry proven and used for a variety of applications including sensors, switches, relays, chargers and other devices requiring a thru-hole mounted package. DIP body sizes range from 9.2x6.4x3.4mm to a maximum of 52.3x13.7x3.4mm and have package thickness of 3.4 and 3.5mm. JCET offers full turnkey assembly and test services for DIP packages.



### Highlights

- Thru-hole mounted package
- Excellent thermal and electrical performance
- Full in-house assembly and test capability

### Features

- DIP body size production ranges from 9.2 x 6.4 x 3.4mm to a maximum of 52.3 x 13.7 x 3.4mm
- Package thicknesses of 3.4 and 3.5mm available
- Si / GaAs / RDL assembly capability

### Standard Materials

- Leadframe PPF / Ag plating / Selective Ag plating
- Wire Gold wire / Cu wire / AuPdCu wire
- Epoxy DAF / Screen print / Conductive / Non-conductive epoxy / Sintering epoxy / Solder paste
- I/O finish Sn plating/PPF

### Applications

- Telecommunications
- Portable
- Sensors
- ESD Protection
- Chargers
- Switch Relays
- Transformers

### Process Highlights

- Package thickness 3.4mm-3.5mm
- Die thickness 290um minimum
- Wire count >10wires
- Die Stack Two

### Package Level Reliability

- Moisture Sensitivity Level NA (Non-applicable to thru-hole)
- Temperature Cycling -65C to 150C, 1000 cycles
- Autoclave 121C / 100%RH/2atm, 168hrs
- High Temperature Storage 150C, 1000 hrs
- HAST 85C / 85% RH, 1000 hrs